

II. AMENDMENTS TO THE CLAIMS:

Please accept amendments to the claims as follows:

1. (Currently amended) A method for the manufacture of a semiconductor device containing a field-effect transistor with a gate electrode (1), a source region (2) and a drain region (3), wherein a gate oxide layer (4) is formed directly on a surface of a semiconductor body (10) of silicon, on which gate oxide layer the gate electrode (1) containing a polycrystalline silicon layer (1) is provided locally, wherein the source region (2) and the drain region (3) are formed, in the semiconductor body (10), on both sides of the gate electrode (1) and a part (3A) of the drain region (3) bordering the gate electrode (1) is provided with a lower doping concentration, and wherein a spacer (5) of a material that can be selectively etched with respect to the gate oxide layer (4), is produced on both sides of the gate electrode (1), characterized in that for the formation of the drain region (3) and the lowly doped part (3A) thereof, two additional mask in layers (6, 7) are deposited on the surface of the semiconductor body (10), the drain region (3) being formed at a distance from the gate electrode (1) that is larger than the width of the spacer (5).

2. (Previously amended) A method as claimed in claim 1, characterized in that for the formation of the lowly doped part (3A) of the drain region (3) a first masking layer (6) extending so far as to be on the gate electrode (1) is produced on the side of the gate electrode (1) of the source region (2) to be formed on the surface of the semiconductor body (10), and a second

masking layer (7) extending from the gate electrode (1) up to the drain region (3) to be formed is produced on the surface of the semiconductor body (10).

3. (Currently amended) A method as claimed in claim 1 characterized in that at the location of the source region (2) and the drain region (3) the gate oxide layer (4) is provided with ~~an~~ aperture apertures (8, 9) and that at the location of the ~~aperture apertures~~ aperture apertures (8, 9) the gate electrode (1) and the source region (2) and the drain region (3) are provided with a metal layer (11), which with the aid of the underlying silicon is converted into a silicide layer (11).

4. (Previously amended) A method as claimed in claim 1, characterized in that the distance from the drain region (3) to the gate electrode (1) is chosen between 1 and 4 μm .

5. (Previously amended) A method as claimed in claim 1, characterized in that on the gate electrode (1) an isolating layer (26) is deposited, on which a shielding electrode (27) is produced at the location of the gate electrode (1).

6. (Previously amended) A method as claimed in claim 1, characterized in that the spacers (5) are formed of a layer (5A) of silicon nitride.

7. (Previously amended) A method as claimed in claim 1, characterized in that the spacers (5) are formed of a layer of silicon nitride (5A) on which a layer (5B) of polycrystalline silicon is deposited.

8. (Previously amended) A method as claimed in claim 1, characterized in that additional semiconductor elements and preferably one or more passive components are integrated into the semiconductor body (10).

9. (Previously cancelled)

10. (New) A method for the manufacture of a semiconductor device containing a field-effect transistor with a gate electrode (1), a source region (2) and a drain region (3), wherein a gate oxide layer (4) is formed directly on an epitaxial layer of a semiconductor body (10) of silicon over the source region and the drain region on which gate oxide layer the gate electrode (1) containing a polycrystalline silicon layer (1) is provided locally, wherein the source region (2) and the drain region (3) are formed, in the semiconductor body (10), on both sides of the gate electrode (1) and a part (3A) of the drain region (3) bordering the gate electrode (1) is provided with a lower doping concentration, and wherein a spacer (5) of a material that can be selectively etched with respect to the gate oxide layer (4), is produced on both sides of the gate electrode (1), characterized in that for the formation of the drain region (3) and the lowly doped part (3A) thereof, two additional mask in layers (6, 7) are deposited on the surface of the semiconductor

body (10), the drain region (3) being formed at a distance from the gate electrode (1) that is larger than the width of the spacer (5).